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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kumar et al.
Serial No.: 09/903,114
Filed: July 11, 2001
For: THERMAL PROCESSING
SYSTEM AND METHODS FOR
FORMING LOW-K DIELECTRIC
FILMS SUITABLE FOR
INCORPORATION INTO
MICROELECTRONIC DEVICES

Examiner: Unknown
Group Art Unit: Unknown
Docket No.: FSI0006/US/2

Commissioner for Patents
Washington, DC 20231

I CERTIFY THAT ON Dec 7, 2001, THIS PAPER IS
BEING DEPOSITED WITH THE U.S. POSTAL SERVICE AS FIRST
CLASS MAIL IN AN ENVELOPE ADDRESSED TO THE
COMMISSIONER FOR PATENTS, WASHINGTON, DC 20231

Paula J. Breeden

INFORMATION DISCLOSURE STATEMENT

The documents listed on the enclosed Form PTO-1449 are presented pursuant to
Applicant's duty of disclosure under 37 C.F.R. 1.56. A copy of each of these documents is
enclosed.

No fee is believed to be necessary for the consideration of this Information
Disclosure Statement since it is being filed before the receipt of an Office Action on the merits. In
case the papers cross in the mail, it is requested that consideration of this Information Disclosure
Statement be given under 37 C.F.R. § 1.97 (c)(2). If any fee is required, please charge our Deposit
Account No. 50-1775 and notify us of the same.

Respectfully Submitted,

Dated: December 7, 2001

By:

David B. Kagan
David B. Kagan, Reg. No. 38,406
KAGAN BINDER, PLLC
Suite 200 Maple Island Building
221 Main Street North
Stillwater, Minnesota 55082
651-275-9804 X 107